

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	2023	resin and harden and humidity	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2003/09/11 09:15
2	BRS	L2	1827	1 and @ay<2000	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2003/09/11 09:18
3	BRS	L3	77	2 and (257/\$.ccls. 438/\$.ccls. 372/\$.ccls.)	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2003/09/11 10:20
4	BRS	L4	63	264/272.17.ccls. and humidity	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2003/09/11 10:29
5	BRS	L5	13	264/272.13.ccls. and humidity	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2003/09/11 10:59
6	BRS	L6	2	264/272.13.ccls. and harden and humidity	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2003/09/11 11:00

	Type	L #	Hits	Search Text	DBs	Time Stamp
7	BRS	L7	13	264/272\$.ccls. and harden and humidity	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2003/09/11 11:25
8	BRS	L8	4729	resin and (heat adj treat\$4) and humidity	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2003/09/11 11:26
9	BRS	L9	234	8 and harden	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2003/09/11 11:27
10	BRS	L10	209	9 and @ay<2000	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2003/09/11 11:39
11	BRS	L11	37	(led (light adj emitting adj diode) laser) and encapsul\$5 and (heat adj treat)	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2003/09/11 12:28